

# Axiom Electronics PCBA Design for Manufacturability Guidelines

Section: 10.17

Revision: B

Revision Date: 11/14/18

DFM Subject: Via Soldermask Encroachment

## DFM Requirement:

- If the PCB will be wave soldered and the via-to-via and via-to-land spacing is  $\leq 0.25\text{mm}$  (0.010") via soldermask encroachment is required. In this case all vias, on both sides of the PCB, shall have encroached soldermask.
- If the PCB will use selective soldering via soldermask encroachment is not required.
- The encroached soldermask opening (diameter) shall be 0.125mm (0.005") larger than the drill diameter. See illustration in detail section.

## DFM Impact:

Via soldermask encroachment helps reduce solder bridging by increasing the gap between exposed metal surfaces. It also reduces the amount of exposed metal.

## DFM Details:

